



Thermoelectrics

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Thermal Grease TG-005

Non-Silicone Compound

Non-curing

Very High Thermal Conductivity

IDEAL FOR:

Thermoelectric and Heatsink Interface

DESCRIPTION:

TG-005 is a re-workable, aluminum nitride filled, electrically insulating and thermally conductive paste which exhibits outstanding thermal transfer in comparison to most adhesives. The non-curing nature of TG-005 makes it ideal as interfacial compound for thermal transfer for thermoelectrics and heat sinks. With one of the highest thermal conductivity and lowest thermal interface resistance among all thermal greases, TG-005 has been proven as the standard in providing system thermal resistance of 0.06°C/W-sq.in. with nominal increase for thickness.

AVAILABILITY:

TG-005 is available in the following quantities.

Model Number	Quantity
TG-005	10 gram jar

APPLICATION PROCEDURES:

- (1) Apply a thin continuous film of grease to module hot side surface or to module area on hot side heat exchanger. A printer's ink roller works well for this.
- (2) Locate module on hot side heat exchanger, hot side down.
- (3) Gently oscillate module back and forth exerting uniform downward pressure, noting efflux of thermal compound around edges of module. Continue motion until resistance is felt.

TYPICAL PROPERTIES

Electrical Resistivity	>1X10 ¹³ ohm-cm
Tensile Elongation (%)	Non-curing
Cured Density (gm/cc)	2.3
Thermal Conductivity	4.0 W/m-°C 28 Btu-in/hr-ft ² -°F
Linear Thermal Expansion Coeff. (ppm/°C)	Non-curing
Maximum Continuous Operation Temp. (°C)	150
Avg. Viscosity(.5 rpm, 24°C)	461,000 cp

CURE SCHEDULES:

Non-Curing

SHELF LIFE:

<u>Storage temperature</u> 25 °C	<u>Shelf Life</u> 1 year
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"USES FOR THERMOELECTRIC COOLING ARE AS LIMITLESS AS THE IMAGINATION"